

AN14570

使用 RT1040-EVK 为 RT104x 进行设计

Rev. 1.0 — 2025年2月12日

应用笔记

文档信息

信息	内容
关键词	AN14570_ZH, RT1041, RT1042, RT1042, RT1046
摘要	本应用说明便于用户方便选择和开发 RT1040 系列。



1 介绍

i.MX RT1040 跨界 MCU 基于 Arm Cortex-M7内核，具有实时性能和高集成功能，适用于工业和物联网应用。

i.MX RT1040 CM7 运行频率高达 600 MHz，内置 512 KB 片上 RAM，可配置为 TCM 或通用存储器使用。该系列提供各种存储器接口和丰富的连接接口，包括 UART、SPI、I²C、USB 和 CAN。i.MX RT1040 采用 169 BGA 紧凑型封装提供更高的灵活性，温度范围扩展至125°C。

目前，RT1040 系列有四个部件编号：RT1041、RT1042、RT1043 和 RT1046。这些部件之间存在一些细微差别，因此编写了本应用说明以方便选择和开发。

2 芯片概述及设计要点

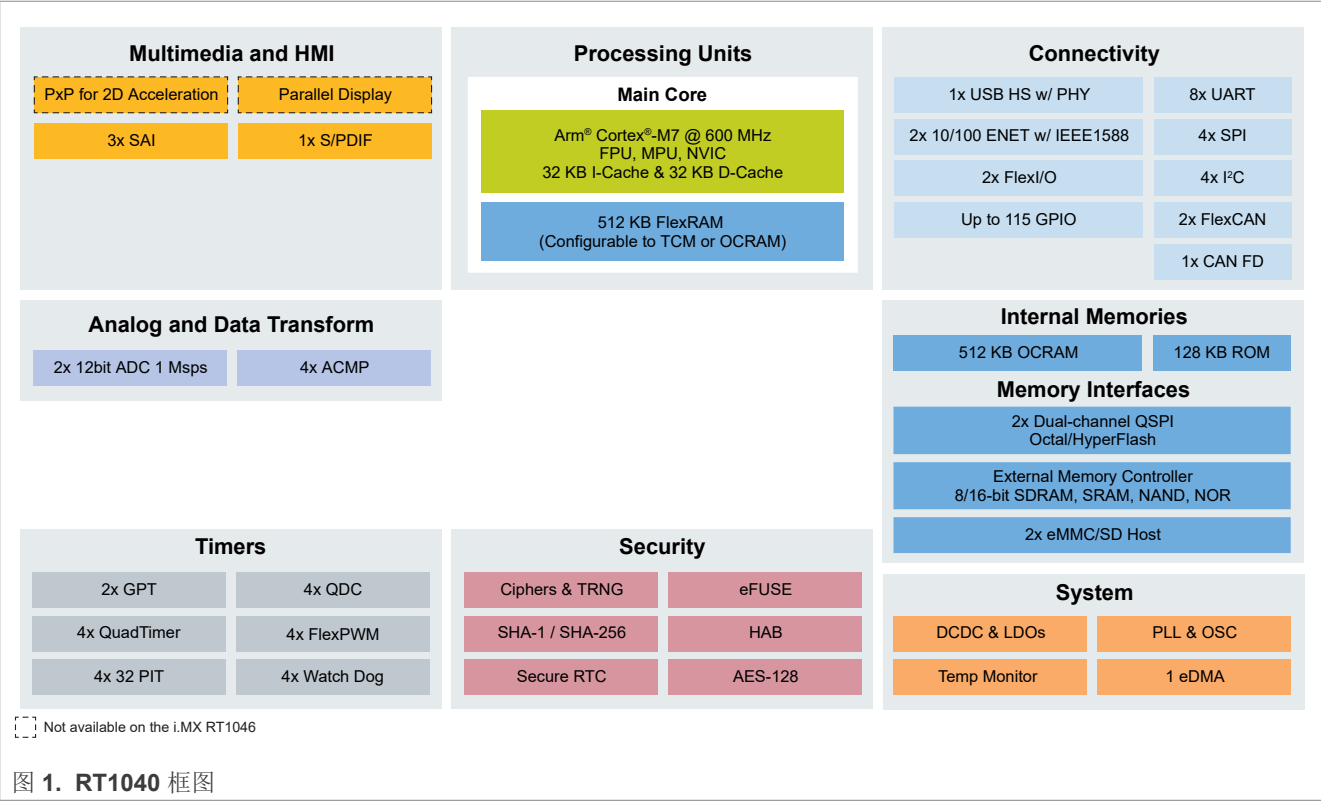


图 1. RT1040 框图

性能方面，消费级芯片可以运行 600 MHz，工业级芯片可以达到 528 MHz。并且全部支持最高 512 KB TCM，为性能要求高的应用保证固定低延迟的内存访问。因此 CPU 性能表现一致，不同型号之间主要差异体现在外设数量、SRAM 存储空间大小、封装类型等方面。

[表 1](#) 简要介绍了不同型号之间的差异。

表 1. RT1040 设备之间的差异

	RT1041	RT1042	RT1043	RT1046
ADC	12 ch	12 ch	12 ch	15 ch
FlexRAM	512 KB	512 KB	512 KB	512 KB
OCRAM	0	0	512 KB	512 KB
ENET	x1	x1	x1	x2

表 1. RT1040 设备之间的差异...续上页

	RT1041	RT1042	RT1043	RT1046
LPSPi	x3	x3	x3	x4
LCD/PXP	N	Y	Y	N
Tj (Commercial)	0 to +95	0 to +95	0 to +95	0 to +95
Tj (Industrial)	-40 to +125	-40 to +125	-40 to +125	-40 to +125
Package	9 × 9 mm, 0.65 mm, BGA169	9 × 9 mm, 0.65 mm, BGA169	9 × 9 mm, 0.65 mm, BGA169	7 × 7 mm, 0.5 mm, BGA169
	11 × 11 mm, 0.8 mm, BGA169	11 × 11 mm, 0.8 mm, BGA169		
注: RT1041/RT1042 9 × 9 和 11 × 11 mm 的 ballmap 分布是不同的。				

根据 表 1 和客户的常见问题，以下是一些设计要点：

- RT1041/RT1042 9 × 9 和 11 × 11 mm 的 ball map 不同。
- RT1040 系列中 7 × 7、9 × 9 和 11 × 11 mm 的 ball map 不同。
- RT1043 = RT1042 + 512 KB OCrAM，但 RT1043 只有 9 × 9 mm 封装。
- 相同封装的 RT1041、RT1042、RT1043 引脚兼容。

3 开发设计参考资料

3.1 硬件

RT1041, RT1042 和 RT1043 可以参考以下设计文件: [RT1040_EVK_Design_Files](#)。

注: RT1040_EVK 设计基于 11 × 11 mm、0.8 mm 和 BGA169 封装的芯片。对于 9 × 9 mm、0.65 mm 间距的 RT1041/RT1042/RT1043 设备，ball map 与 RT1040_EVK 上的 ball map 不同，客户应参考 RT1040 数据表中的符号封装信息。

RT1046 可以参考以下设计文件: [RT1046_EVK_Design_Files](#)。

3.2 软件

对于 RT1041 和 RT1042，用户可以直接使用 RT1040 SDK 进行开发。.

RT1043 内部有比 RT1042 更大的 SRAM 空间（ 512 KB FlexRAM + 512 KB OCrAM）。基于这一点，用户可以使用 RT1040 的 SDK 并将 linker 文件替换为 RT1060 的 linker 文件即可。或者用户可以直接使用 RT1060 SDK。

对于 RT1046，建议使用 RT1060 SDK。

4 修订记录

[表 2](#) 汇总了自初始版以来对本文档所做的更改。

表 2. 修订记录

文档号	日期	说明
AN14570_ZH v.1.0	2025 年 2 月 12 日	初次发布

Legal information

Definitions

Draft — A draft status on a document indicates that the content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included in a draft version of a document and shall have no liability for the consequences of use of such information.

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <https://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Suitability for use in non-automotive qualified products — Unless this document expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

HTML publications — An HTML version, if available, of this document is provided as a courtesy. Definitive information is contained in the applicable document in PDF format. If there is a discrepancy between the HTML document and the PDF document, the PDF document has priority.

Translations — A non-English (translated) version of a document, including the legal information in that document, is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

Security — Customer understands that all NXP products may be subject to unidentified vulnerabilities or may support established security standards or specifications with known limitations. Customer is responsible for the design and operation of its applications and products throughout their lifecycles to reduce the effect of these vulnerabilities on customer's applications and products. Customer's responsibility also extends to other open and/or proprietary technologies supported by NXP products for use in customer's applications. NXP accepts no liability for any vulnerability. Customer should regularly check security updates from NXP and follow up appropriately. Customer shall select products with security features that best meet rules, regulations, and standards of the intended application and make the ultimate design decisions regarding its products and is solely responsible for compliance with all legal, regulatory, and security related requirements concerning its products, regardless of any information or support that may be provided by NXP.

NXP has a Product Security Incident Response Team (PSIRT) (reachable at PSIRT@nxp.com) that manages the investigation, reporting, and solution release to security vulnerabilities of NXP products.

NXP B.V. — NXP B.V. is not an operating company and it does not distribute or sell products.

Trademarks

Notice: All referenced brands, product names, service names, and trademarks are the property of their respective owners.

NXP — wordmark and logo are trademarks of NXP B.V.

AMBA, Arm, Arm7, Arm7TDMI, Arm9, Arm11, Artisan, big.LITTLE, Cordio, CoreLink, CoreSight, Cortex, DesignStart, DynamIQ, Jazelle, Keil, Mali, Mbed, Mbed Enabled, NEON, POP, RealView, SecurCore, Socrates, Thumb, TrustZone, ULINK, ULINK2, ULINK-ME, ULINK-PLUS, ULINKpro, μ Vision, Versatile — are trademarks and/or registered trademarks of Arm Limited (or its subsidiaries or affiliates) in the US and/or elsewhere. The related technology may be protected by any or all of patents, copyrights, designs and trade secrets. All rights reserved.

Microsoft, Azure, and ThreadX — are trademarks of the Microsoft group of companies.

内容

1 介绍2

2 芯片概述及设计要点2

3 开发设计参考资料3

3.1 硬件3

3.2 软件3

4 修订记录4

Legal information5

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.